

PRODUCT BRIEF | VT-Stack Packaging

MEMORY STACKING FOR EMBEDDED SOLUTIONS

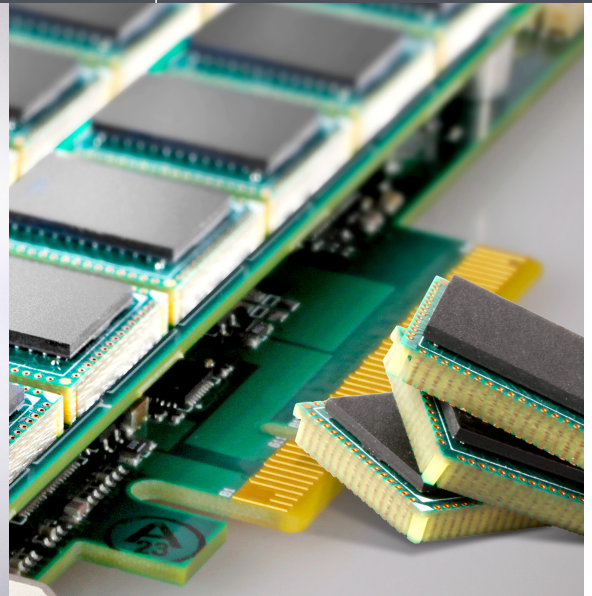
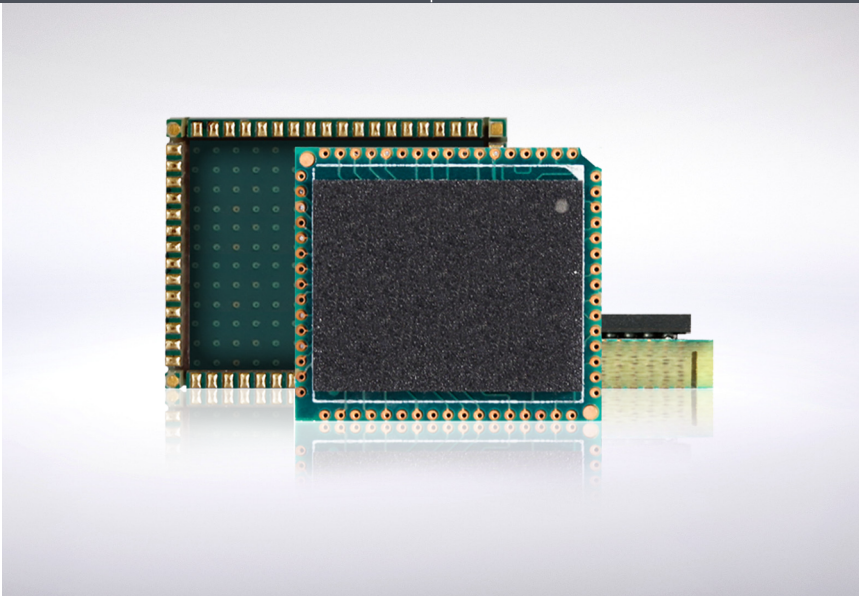
Viking Technology's 3rd Generation of Patented stacking, the VT-Stack™, enables OEM customers that are designing solutions with DRAM, NAND Flash or even next generation memory technologies such as MRAM, to optimize the performance and design cycle of their products.

FEATURES

- ▶ Increased memory capacity
- ▶ Cost Effective
- ▶ Faster Time-to-Market (TTM)
- ▶ Stacking design support: DRAM, NAND & Persistent Memories

APPLICATIONS SERVED

Enterprise markets – Highest DRAM Capacity Support	Embedded/Industrial markets – Ultra small form factor capacity	Military – SWaP Optimized
High Density SSD (Card, Module, Down-Board)	Embedded Products (uServer, Industrial PCs)	AdvancedTCA, MicroTCA



MEMORY STACKING FOR EMBEDDED SOLUTIONS

DRAM STACKING

Designing the highest density memory module solutions typically requires multi-die packaged DRAM (DDP or QDP). These multi-die packaged DRAMs have significant cost premiums, due to compound yield loss at test. Viking's VT-Stack™ Technology allows for ultimate flexibility of configuration, lower cost of device, and most importantly supply chain flexibility.

VT-Stack™ Technology supports high density DIMMs for servers in enterprise markets, as well as small form factor solutions for telecommunication, embedded and industrial markets.

DRAM MODULES WITH VT-STACK

FORM FACTOR	TECHNOLOGY	SPEED	DENSITIES
LRDIMM	DDR4/DDR3	Up to 2666 MT/s	Up to 128GB
RDIMM	DDR4/DDR3	Up to 2666 MT/s	Up to 128GB
VLP RDIMM	DDR4/DDR3	Up to 2666 MT/s	Up to 64GB
VLP MiniRDIMM	DDR4/DDR3	Up to 2666 MT/s	Up to 64GB
VLP SORDIMM	DDR4/DDR3	Up to 2666 MT/s	Up to 64GB

FLASH STACKING

VT-Stack™ Technology for NAND Flash allows for the highest capacity solutions in the smallest volume. Whether the interface is PCIe, SAS, SATA or other, Viking's VT-Stack™ Technology can double the capacity of the drive within the same footprint.

VT-Stack™ Technology for NAND Flash supports higher density designs to enable form factors such as PCIe Half-height/Half-length. The design also allows for SLC, MLC and TLC support with conformal coating options.

For price and availability, please email us at sales@vikingtechnology.com.



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